



Material Content Data Sheet



Sales Product Name		TLS810B1EJ V33		Issued		13. August 2019		
MA#		MA001699980						
Package		PG-DSO-8-52		Weight*		83.68 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.996	1.19	1.19	11902	11902
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		109	
	non noble metal	zinc	7440-66-6	0.036	0.04		435	
	non noble metal	iron	7439-89-6	0.728	0.87		8696	
wire	non noble metal	copper	7440-50-8	29.548	35.31	36.23	353107	362347
	non noble metal	copper	7440-50-8	0.046	0.05	0.05	546	546
	encapsulation	organic material	carbon black	1333-86-4	0.101	0.12		1207
plastics	plastics	epoxy resin	-	4.647	5.55		55530	
	inorganic material	silicondioxide	60676-86-0	45.760	54.69	60.36	546850	603587
leadfinish	non noble metal	tin	7440-31-5	0.695	0.83	0.83	8307	8307
plating	noble metal	silver	7440-22-4	0.725	0.87	0.87	8658	8658
glue	plastics	epoxy resin	-	0.097	0.12		1163	
	noble metal	silver	7440-22-4	0.292	0.35	0.47	3490	4653
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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